

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6525513

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HAO-CHENG HOU	01/13/2021
WEI-YU CHEN	01/15/2021
JUNG-WEI CHENG	01/24/2021
TSUNG-DING WANG	01/13/2021
CHIEN-HSUN LEE	01/14/2021
CHUNG-SHI LIU	01/13/2021
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17144061
CORRESPONDENCE DATA	
Fax Number:	(949)391-4699
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	886223692800
Email:	usa@jcipgroup.com
Correspondent Name:	JCIPRNET
Address Line 1:	8F-1, NO. 100, ROOSEVELT RD. SEC. 2,
Address Line 4:	TAIPEI, TAIWAN 100404
ATTORNEY DOCKET NUMBER:	104945-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	02/01/2021
Total Attachments: 2	

source=104945_DCL_ASSN#page1.tif

source=104945_DCL_ASSN#page2.tif

DECLARATION AND ASSIGNMENT

Title of Invention: SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD THEREOF

As a below named inventor, or one of the below named joint inventors, I hereby declare that:

This declaration and assignment is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application No. or PCT International Application No.: 17/144,061 , filed on 2021-01-07

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. §1.56.

All statements made of my own knowledge are true and all statements made on information and belief are believed to be true.

I hereby acknowledge that any willful false statement made in this declaration may jeopardize the validity of the application or any patent issuing thereon and is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

The above-identified invention shall henceforth be referred to herein as the "INVENTION" and the above-identified application shall henceforth be referred to herein as the "APPLICATION."

Taiwan Semiconductor Manufacturing Company, Ltd., a corporation organized and existing under the laws of Taiwan, with its principal office at 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, 300-78, Taiwan and its heirs, successors, legal representatives and assigns shall henceforth be referred to collectively herein as ASSIGNEE.

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have assigned and do hereby assign to ASSIGNEE, its successors and assigns, my entire right, title and interest in and to said INVENTION and in and to said APPLICATION and all patents which may be granted therefor, and all future non-provisional applications including, but not limited to, divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said INVENTION, or patents resulting therefrom, insofar as my interest is concerned, to ASSIGNEE, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

Additionally, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have also assigned and hereby assign to ASSIGNEE, its successors and assigns, all of my rights to the INVENTION disclosed in said APPLICATION, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and I further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to ASSIGNEE, or to its successors, assigns, and legal representatives, any facts known to me respecting said INVENTION or the file history thereof, and at the expense of ASSIGNEE, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid ASSIGNEE, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

I hereby grant the attorney of record the power to insert on this document any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year.

1. NAME OF INVENTOR (Full Legal Name): <u>Hao-Cheng Hou</u> Signature: <u>/ Hao-Cheng Hou</u> / Date: <u>1/13/2021</u>
2. NAME OF INVENTOR (Full Legal Name): <u>Wei-Yu Chen</u> Signature: <u>/ Wei-Yu Chen</u> / Date: <u>1/15/2021</u>
3. NAME OF INVENTOR (Full Legal Name): <u>Jung-wei Cheng</u> Signature: <u>/ Jung-wei Cheng</u> / Date: <u>1/24/2021</u>
4. NAME OF INVENTOR (Full Legal Name): <u>Tsung-Ding Wang</u> Signature: <u>/ Tsung-Ding Wang</u> / Date: <u>1/13/2021</u>
5. NAME OF INVENTOR (Full Legal Name): <u>Chien-Hsun Lee</u> Signature: <u>/ Chien-Hsun Lee</u> / Date: <u>1/14/2021</u>
6. NAME OF INVENTOR (Full Legal Name): <u>Chung-Shi Liu</u> Signature: <u>/ Chung-Shi Liu</u> / Date: <u>1/13/2021</u>